	Type	Hits	Search Text	DBs
1	BRS	379987	wafer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
2	BRS	8628	obverse	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
3	BRS	825439	reverse	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
4	BRS	827751	S2 or S3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
5	BRS	7040	S1 same S4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
6	BRS	277674	nitride or GaN	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
7	BRS	161	S5 same S6	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
8	BRS	5782	(slanting or slanted) near4 edge	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
9	BRS	114	S7 and "9"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
10	BRS	5	S7 and S8	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
11	BRS	886	257/620	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB

	Type	Hits	Search Text	DBs
12	BRS	9661	S1 near7 S6	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
13	BRS	5	S8 same S12	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
14	BRS	0	S13 not S10	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
15	BRS	159	S12 near7 edge	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
16	BRS	40927	wafer.clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
17	BRS	1721	Gan.clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
18	BRS	148	S16 and S17	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
19	BRS	366103	"257"/$.ccls. or "438"/$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
20	BRS	113	S18 and S19	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
21	BRS	35	S18 not S20	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
22	BRS	977360	S11 ro S22 or S23 or S24	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB

	Type	Hits	Search Text	DBs
23	BRS	2357	S11 or S22 or S23 or S24	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
24	BRS	816	257/618	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
25	BRS	658	257/627	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
26	BRS	314	257/628	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
27	BRS	42	S8 same S1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
28	BRS	42	S27 not S21	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
29	BRS	8630	obverse	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
30	BRS	380198	wafer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
31	BRS	58864	posture	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
32	BRS	207	S29 same S30	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
33	BRS	4	S31 same S32	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB

	Type	Hits	Search Text	DBs
34	BRS	10070	laser near3 (mark or marking)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
35	BRS	1	S32 same S34	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
36	BRS	1	S32 same S35	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
37	BRS	2	S32 and S34	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
38	BRS	8630	S29	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
39	BRS	3	S34 same S38	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
40	BRS	841	S34 same S30	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
41	BRS	1	S40 and S38	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
42	BRS	825788	reverse	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
43	BRS	108	S40 and S42	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
44	BRS	733	S40 not S43	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB

	Type	Hits	Search Text	DBs
45	BRS	43	obverse same inverse	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
46	BRS	2	S45 same wafer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
47	BRS	3	S45 and wafer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
48	BRS	180317	inverse	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
49	BRS	825788	reverse	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
50	BRS	3288	discriminative	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
51	BRS	12	(S48 or S49) near4 S50	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
52	BRS	184	(S48 or S49) same S30 same (mark or marking)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
53	BRS	4815	257/787	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
54	BRS	272	(S48 or S49) and S53	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
55	BRS	65	S30 and S54	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB